



Product Change Notification / JAON-13JEGV932

Date:

26-May-2016

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers, 8-bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors, Digital Potentiometers, Digital to Analog Converters, Interface-Passive-Keyless-Entry Analog Front End, KEELOQ® Encoder Devices, Linear Comparators, Linear Op Amps, Memory, USB Bridge

PCN Type:

Manufacturing Change

Notification Subject:

CCB 1836 Final Notice: Qualification of CuPdAu bond wire in selected products of the 120K, 150K, 160K and 200K wafer technologies available in 14L TSSOP package at MMT assembly site.

Notification Text:

PCN Status: Final notification

Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K, 150K, 160K and 200K wafer technologies available in 14L TSSOP package at MMT assembly site.

Pre Change: Gold (Au) or Palladium coated copper wire (PdCu) bond wire

Post Change: Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT assembly site	MMT assembly site
Wire material	Au wire or PdCu wire	CuPdAu wire
Die attach material	2200D	2200D
Molding compound material	G600V	G600V
Lead frame material	C7025	C7025

Impacts to Data Sheet: None

Reason for Change: To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status: In Progress

Estimated First Ship Date: June 6, 2016 (date code: 1623)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

WW	January 2016				----->				May 2016				June 2016				
	01	02	03	04					18	19	20	21	22	23	24	25	26
Initial PCN Issue Date		X															
Qual Report Availability											X						
Final PCN Issue Date											X						
Implementation Date													X				

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History: **January 13, 2016:** Issued initial notification. **May 26, 2016:** Issued final notification. Attached the qualification report. Updated the scope to include selected products of the 120K, 150K, 160K and 200K wafer technologies available in 14L TSSOP package at MMT assembly site. Revised the estimated first ship date from April 20, 2016 to June 6, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-13JEGV932_Qual_Report.pdf](#)
[PCN_JAON-13JEGV932_Affected_CPN.pdf](#)
[PCN_JAON-13JEGV932_Affected_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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